### 1.0A Surface Mount Super

Fast Rectifiers-50-600V

## Features

- Glass passivated device
- Ideal for surface mouted applications
- Low reverse leakage
- Metallurgically bonded construction
- High temperature soldering guaranteed: $250^{\circ} \mathrm{C} / 10$ seconds, $0.375^{\prime \prime}(9.5 \mathrm{~mm})$ lead length, 5 lbs . $(2.3 \mathrm{~kg}$ ) tension
- Compliant to RoHS Directive 2011/65/EU
- Compliant to Halogen-free


## Mechanical data

- Case : JEDEC SOD-123 molded plastic body over passivated chip
- Terminals: Plated axial leads, solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode end
- Mounting Position: Any


## Package outline



Maximum ratings and Electrical Characteristics ( $A T T_{A}=25^{\circ} \mathrm{C}$ unless otherwise noted)

| PARAMETER | CONDITIONS | Symbol | MIN. | TYP. | MAX. | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Forward rectified current | See Fig. 2 | I。 |  |  | 1.0 | A |
| Forward surge current | $8.3 \mathrm{~ms} \mathrm{single} \mathrm{half} \mathrm{sine-wave} \mathrm{(JEDEC} \mathrm{methode)}$ | $\mathrm{I}_{\text {FSM }}$ |  |  | 25 | A |
| Reverse current | $\mathrm{V}_{\mathrm{R}}=\mathrm{V}_{\text {RRM }} \mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ | $I_{R}$ |  |  | 5.0 | $\mu \mathrm{A}$ |
|  | $\mathrm{V}_{\mathrm{R}}=\mathrm{V}_{\text {RRM }} \mathrm{T}_{\mathrm{A}}=100^{\circ} \mathrm{C}$ |  |  |  | 50 |  |
| Thermal resistance | Junction to ambient NOTE 1 | $\mathrm{R}_{\text {OJA }}$ |  | 85 |  | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| Diode junction capacitance | $\mathrm{f}=1 \mathrm{MHz}$ and applied 4V DC reverse voltage | C |  | 10 |  | pF |
| Storage temperature |  | $\mathrm{T}_{\text {ste }}$ | -65 |  | +150 | ${ }^{\circ} \mathrm{C}$ |


| SYMBOLS | $\begin{aligned} & \mathrm{V}_{\text {RRM }}{ }^{* 1} \\ & (\mathrm{~V}) \end{aligned}$ | $\begin{aligned} & \mathrm{V}_{\text {Rus }}{ }^{* 2} \\ & (\mathrm{~V}) \end{aligned}$ | $\begin{aligned} & \mathrm{V}_{\mathrm{R}}^{*} \\ & (\mathrm{~V}) \end{aligned}$ | $\begin{aligned} & V_{F}^{* 4} \\ & (\mathrm{~V}) \end{aligned}$ | $\begin{aligned} & \mathrm{t}_{\text {(ns }}^{* 5} \\ & \text { (ns) } \end{aligned}$ | Operating temperature $\mathrm{T}_{\mathrm{J}},\left({ }^{\circ} \mathrm{C}\right)$ |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| DSF1A | 50 | 35 | 50 | 0.95 | 35 | -55 to +150 |
| DSF1B | 100 | 70 | 100 |  |  |  |
| DSF1C | 150 | 105 | 150 |  |  |  |
| DSF1D | 200 | 140 | 200 |  |  |  |
| DSF1E | 300 | 210 | 300 | 1.25 |  |  |
| DSF1G | 400 | 280 | 400 |  |  |  |
| DSF1J | 600 | 420 | 600 | 1.70 |  |  |

Note: 1. P.C.B. mounted with $0.2 \times 0.2^{\prime \prime}(5.0 \times 5.0 \mathrm{~mm})$ copper pad areas
2. Reverse recovery time test condition, $\mathrm{I}_{\mathrm{F}}=0.5 \mathrm{~A}, \mathrm{I}_{\mathrm{R}}=1.0 \mathrm{~A}, \mathrm{I}_{\mathrm{R}}=0.25 \mathrm{~A}$

## Rating and characteristic curves

FIG.1-TYPICAL FORWARD


FIG.3- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTICS


NOTES: 1. Rise Time $=7$ ns max., Input Impedance $=1$ megohm. 22 pF .

$$
\text { 2. Rise Time }=10 \text { ns max., Source Impedance }=50 \text { ohms }
$$


$50 / 10 \mathrm{~ns} / \mathrm{cm}$

FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT


FIG.5-TYPICAL JUNCTION CAPACITANCE


## Pinning information

| Pin | Simplified outline | Symbol |
| :---: | :---: | :---: |
| Pin1 cathode <br> Pin2 anode | 1 | $\square$ |

## Marking

| Type number | Marking code |
| :---: | :---: |
| DSF1A | E1A |
| DSF1B | E1B |
| DSF1C | E1C |
| DSF1D | E1D |
| DSF1E | E1E |
| DSF1G | E1G |
| DSF1J | E1J |

## Suggested solder pad layout



Dimensions in inches and (millimeters)

| PACKAGE | A | B | C |
| :---: | :---: | :---: | :---: |
| SOD-123 | $0.075(1.90)$ | $0.055(1.40)$ | $0.075(1.90)$ |

